Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2829	257/786	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 18:46
L2	5447	257/778	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 18:46
S1	1	"20050056950"	US-PGPUB; USPAT	OR	OFF	2005/10/31 12:12
S2	289	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3 or indentation or dent\$3)	USPAT	OR	ON	2005/10/31 12:14
S3	1463	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3 or indentation or dent\$3 or recessed or recess\$3 or depress\$3)	USPAT	OR	ON	2005/10/31 12:14
S4	13	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3) with (indentation or dent\$3 or recessed or recess\$3 or depress\$3)	USPAT	OR	ON	2005/10/31 12:32
S5	5	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3) with (indentation or dent\$3 or project\$3 or protrut\$3)	USPAT	OR	ON	2005/10/31 12:33
S6	5	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3 or wdg\$3) with (indentation or dent\$3 or project\$3 or protrut\$3)	USPAT	OR	ON	2005/10/31 12:33
S7	28	("led" light near emit\$4 or diode or sensor) same substrate with (slop\$3 or hill\$3 or inclin\$3) with (indentation or dent\$3 or project\$3 or protrut\$3)	USPAT	OR	ON	2005/10/31 12:45
S8	5	("20040008326" "20040021831" "6259423" "6741228" "6805448").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 12:39

S9	31	("20040070558" "4547702" "4963788" "4975692" "5013967" "5073446" "5151629" "5170194" "5229883" "5276380" "5294870" "5396304" "5406172" "5504599" "5528339" "5568417" "5594463" "5598067" "5634835" "5637359" "5643642" "5841494" "5847506" "5865521" "5958609" "6140571" "6188175" "6291942" "6337542" "6384804" "RE36060").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 12:41
S10	1997	("led" light near emit\$4 or diode or sensor) same substrate with (indentation or dent\$3 or project\$3 or protrut\$3)	USPAT	OR	ON	2005/10/31 12:45
S11	399	("led" light near emit\$4 or diode or sensor) same substrate with (indentation or dent\$3 or project\$3 or protrut\$3) with (layer or film)	USPAT	OR	ON	2005/10/31 12:45
S12	9	("led" light near emit\$4 or diode or sensor) same substrate same (indentation or dent\$3 or project\$3 or protrut\$3) with clad\$3 near (layer or film)	USPAT	OR	ON	2005/10/31 12:46
S13	1	"20050056950"	US-PGPUB; USPAT	OR	ON	2005/11/15 15:12
S14	2	"6580163".pn. or "3868608".pn.	USPAT	OR	OFF	2005/11/28 00:44
S15	327	(semiconductor or die or dice or IC or chip) with saw near filter	USPAT	OR	ON	2006/04/11 13:00
S16	327	(semiconductor or die or dice or IC or chip) with saw near filters	USPAT	OR	ON	2006/04/11 13:49
S17	294	(semiconductor or die or dice or IC or chip) and filters and satellite with receiv\$3 and terrestrial with receiv\$3	USPAT	OR	ON	2006/04/11 13:50
S18	23	(semiconductor or die or dice or IC or chip) and saw with filters and satellite with receiv\$3 and terrestrial with receiv\$3	USPAT	OR	ON	2006/04/11 13:54

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S19	49	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filters and satellite with receiv\$3 and terrestrial with receiv\$3	USPAT	OR	ON	2006/04/11 16:06
S20	41	S19 not S18	USPAT	OR	ON	2006/04/11 13:55
S21	95	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filters and satellite with receiv\$3 and terrestrial	USPAT	OR	ON	2006/04/11 16:07
S22	49	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filters and satellite with receiv\$3 and terrestrial with receiv\$3	USPAT	OR	ON	2006/04/11 16:17
S23	46	S21 not S22	USPAT	OR	ON	2006/04/11 16:07
S24	55	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filters and satellite and terrestrial with receiv\$3	USPAT	OR	ON	2006/04/11 16:18
S25	149	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filters and satellite and terrestrial	USPAT	OR	ON	2006/04/12 12:51
S26	54	S25 not S21	USPAT	OR	ON	2006/04/11 16:18
S27	149	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filter and satellite and terrestrial	USPAT	OR	ON	2006/04/12 12:51
-S28	768	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filter and satellite	USPAT	OR	ON	2006/04/12 14:22
S29	619	S28 not S27	USPAT	OR	ON	2006/04/12 12:52
S30	1412	("RF" or radio) with (semiconductor or die or dice or IC or chip) and filter with input and filter with output	USPAT	OR	ON	2006/04/12 14:23
S31	191	("RF" or radio) with (semiconductor or die or dice or IC or chip) same filter with input and filter with output	USPAT	OR	ON	2006/04/12 14:23
S32	238	("RF" or radio) with (semiconductor or die or dice or IC or chip) and (pad or contact or terminal) with filter with input and filter with output with (pad or contact or terminal)	USPAT	OR	ON	2006/04/12 16:49

S33	2	"11269284"	JPO	OR	OFF	2006/04/12 16:08
S34	6	("3755761" "3831116" "3858118" "4054841" "4115744").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/12 16:44
S35	5	("4296391").URPN.	USPAT	OR	OFF	2006/04/12 16:44
S36	52	("RF" or radio) with (semiconductor or die or dice or IC or chip) and (acoustic near wave with filter) and (pad)	USPAT	OR	ON	2006/04/12 17:09
S37	9	("4163201" "4737742" "4795934" "5202652" "5252882" "5281883" "5459368" "5949305" "6078229").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/12 17:00
S38	5	("6339365").URPN.	USPAT	OR	OFF	2006/04/12 16:57
S39	206	("RF" or radio) with (semiconductor or die or dice or IC or chip) and (acoustic near wave with filter or saw) and (pad)	USPAT	OR	ON	2006/04/12 17:10
S40	89	("RF" or radio) with (semiconductor or die or dice or IC or chip) and (acoustic near wave with filter or saw near device) and (pad)	USPAT	OR	ON	2006/04/12 17:10
S41	144	("RF" or radio or saw) with (semiconductor or die or dice or IC or chip) and (acoustic near wave with filter) and (pad)	USPAT	OR	ON	2006/04/12 17:15
S42	45	("RF" or radio or saw) with (semiconductor or die or dice or IC or chip) and (acoustic near wave with filter) and (pad) and (semiconductor or silicon or "Si") with substrate	USPAT	OR	ON	2006/04/12 19:22
S43	4424	257/778	USPAT	OR	OFF	2006/04/13 14:13
S44	286	(acoustic or saw) with (semiconductor or die or dice or IC or chip) and filter and (pad) and (semiconductor or silicon or "Si") with substrate	USPAT	OR	ON	2006/04/12 19:23
S45	2665	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 18:04

S46	3417	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:18
S47	3	257/E23.052	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:17
S48	5	257/E23.079	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:18
S49	8	257/E23.052	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:17
S50	10	257/E23.079	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:18
S51	3732	257/686	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/14 17:18